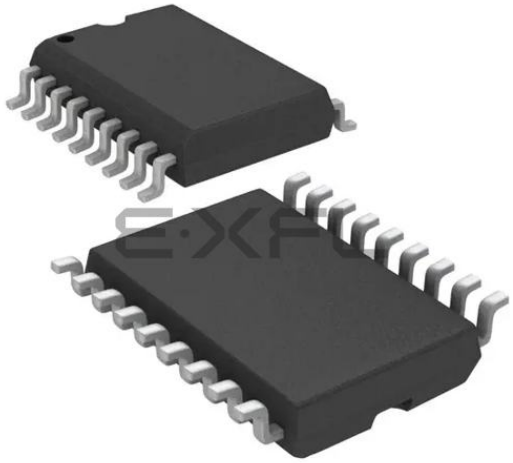
Microchip Technology - DSPIC33FJ06GS101AT-E/SO Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

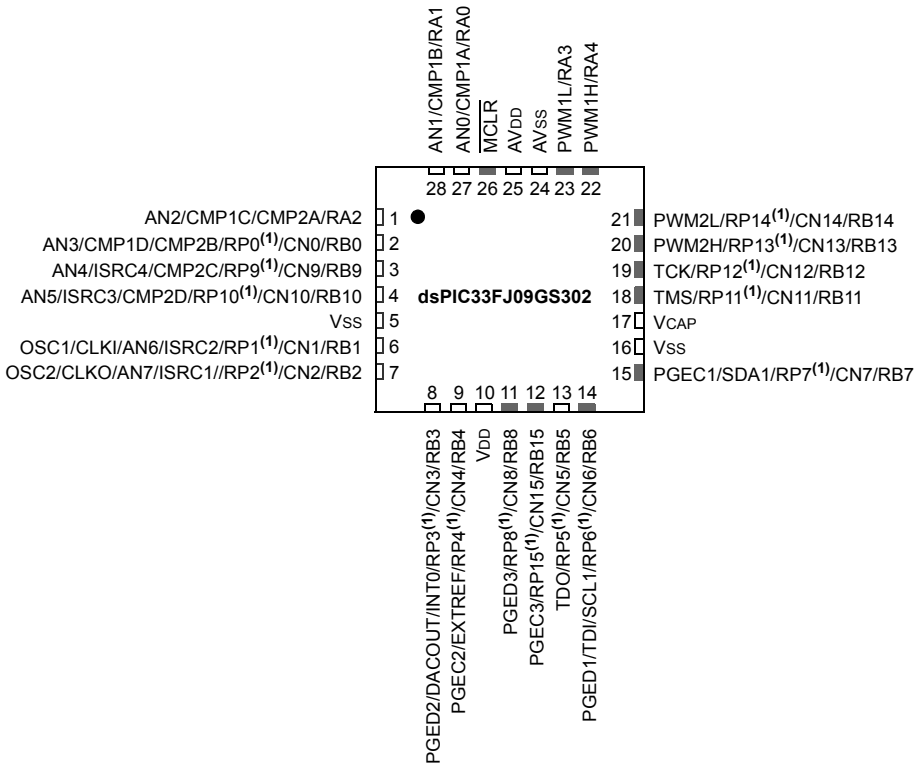
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	6KB (2K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj06gs101at-e-so

Pin Diagrams (Continued)

28-Pin QFN-S(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 family of 16-bit Digital Signal Controllers (DSCs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, regardless if ADC module is not used
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP™ Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

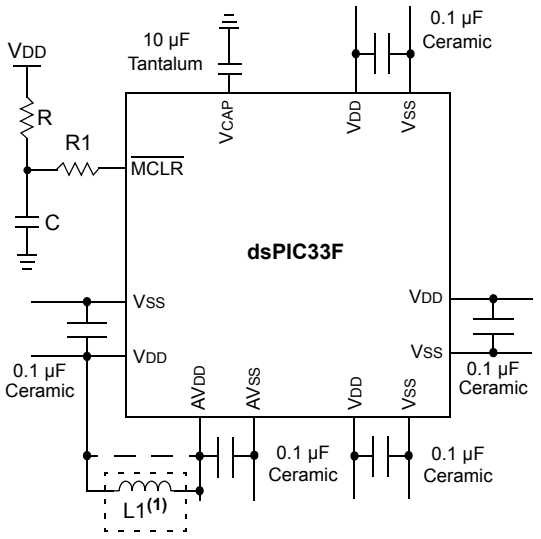
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, upward of tens of MHz, add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible; for example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2} \quad \text{(i.e., ADC conversion rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device; typical values range from 4.7 µF to 47 µF.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

A low-ESR (<0.5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 25.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 22.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides for two specific device functions:

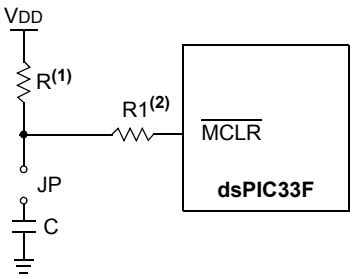
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

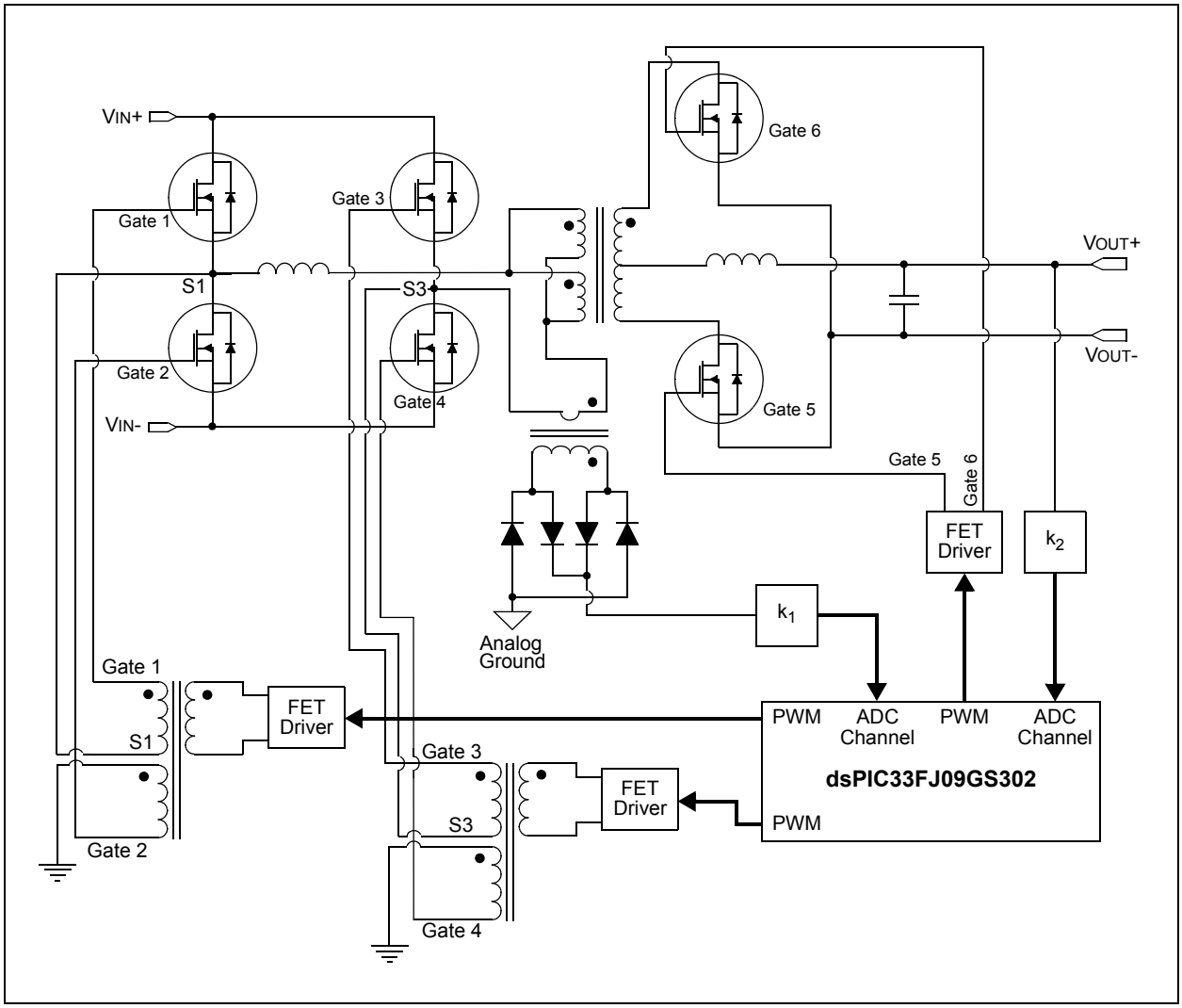
FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

FIGURE 2-8: PHASE-SHIFTED FULL-BRIDGE CONVERTER



REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Trap Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as '0'

bit 4 **MATHERR:** Math Error Trap Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

REGISTER 7-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
—	—	ADIF	U1TXIF(1)	U1RXIF(1)	SPI1IF(1)	SPI1EIF(1)	—
bit 15							bit 8

R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
T2IF	—	—	—	T1IF	OC1IF(1)	IC1IF(2)	INT0IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ADIF:** ADC Group Conversion Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12 **U1TXIF:** UART1 Transmitter Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **U1RXIF:** UART1 Receiver Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10 **SPI1IF:** SPI1 Event Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 9 **SPI1EIF:** SPI1 Error Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8 **Unimplemented:** Read as '0'

bit 7 **T2IF:** Timer2 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6-4 **Unimplemented:** Read as '0'

bit 3 **T1IF:** Timer1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **OC1IF:** Output Compare Channel 1 Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **IC1IF:** Input Capture Channel 1 Interrupt Flag Status bit(2)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **INT0IF:** External Interrupt 0 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

Note 1: This bit is not implemented in the dsPIC33FJ06GS001 device.
2: This bit is not implemented in dsPIC33FJ06GS001/101A/102A devices.

10.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "I/O Ports"** (DS70193) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

All of the device pins (except VDD, VSS, $\overline{\text{MCLR}}$ and OSC1/CLKI) are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

10.1 Parallel I/O (PIO) Ports

Generally a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through", in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 10-1 shows how ports are shared with other peripherals and the associated I/O pin to which they are connected.

When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. That means the corresponding LATx and TRISx registers and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

10.6.2.3 Virtual Pins

Four virtual RPn pins (RP32, RP33, RP34 and RP35) are supported, which are identical in functionality to all other RPn pins, with the exception of pinouts. These four pins are internal to the devices and are not connected to a physical device pin.

These pins provide a simple way for inter-peripheral connection without utilizing a physical pin. For example, the output of the analog comparator can be connected to RP32 and the PWM Fault input can be configured for RP32 as well. This configuration allows the analog comparator to trigger PWM Faults without the use of an actual physical pin on the device.

10.6.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. dsPIC33F devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- Continuous state monitoring
- Configuration bit pin select lock

10.6.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear IOLOCK, a specific command sequence must be executed:

1. Write 0x46 to OSCCON<7:0>.
2. Write 0x57 to OSCCON<7:0>.
3. Clear (or set) IOLOCK as a single operation.

Note: MPLAB® C30 provides built-in C language functions for unlocking the OSCCON register:

```
__builtin_write_OSCCONL(value)
__builtin_write_OSCCONH(value)
```

See the MPLAB C30 Help files for more information.

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all of the Peripheral Pin Selects to be configured with a single unlock sequence, followed by an update to all control registers, then locked with a second lock sequence.

10.6.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a Configuration Mismatch Reset will be triggered.

10.6.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPINRx and RPORx registers. The IOL1WAY (FOSC<5>) Configuration bit blocks the IOLOCK bit from being cleared, after it has been set once. If IOLOCK remains set, the register unlock procedure will not execute and the Peripheral Pin Select Control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the Peripheral Pin Select registers.

13.1 Input Capture Registers

REGISTER 13-1: IC1CON: INPUT CAPTURE 1 CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0
ICTMR(1)	ICI<1:0>		ICOV	ICBNE	ICM<2:0>		
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ICSIDL:** Input Capture Module Stop in Idle Control bit
1 = Input capture module halts in CPU Idle mode
0 = Input capture module continues to operate in CPU Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **ICTMR:** Input Capture Timer Select bit(1)
1 = TMR2 contents are captured on capture event
0 = Reserved

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

bit 4 **ICOV:** Input Capture Overflow Status Flag bit (read-only)
1 = Input capture overflow occurred
0 = No input capture overflow occurred

bit 3 **ICBNE:** Input Capture Buffer Empty Status bit (read-only)
1 = Input capture buffer is not empty, at least one more capture value can be read
0 = Input capture buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits
111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode. Rising edge detect only; all other control bits are not applicable.
110 = Unused (module disabled)
101 = Capture mode, every 16th rising edge
100 = Capture mode, every 4th rising edge
011 = Capture mode, every rising edge
010 = Capture mode, every falling edge
001 = Capture mode, every edge (rising and falling). ICI<1:0> bits do not control interrupt generation for this mode.
000 = Input capture module is turned off

Note 1: This bit is not available in dsPIC33FJ06GS001/101A/102A devices.

REGISTER 15-11: DTRx: PWMx DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTRx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **DTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

REGISTER 15-12: ALTDTRx: PWMx ALTERNATE DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	ALTDTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALTDTR <7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **ALTDTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

REGISTER 15-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IFLTMOD	CLSRC<4:0>(2,3)					CLPOL(1)	CLMOD
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLTSRC<4:0>(2,3)					FLTPOL(1)	FLTMOD<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **IFLTMOD:** Independent Fault Mode Enable bit
1 = Independent Fault mode: Current-limit input maps FLTDAT<1> to PWMxH output and Fault input maps FLTDAT<0> to PWMxL output. The CLDAT<1:0> bits are not used for override functions.
0 = Normal Fault mode: Current-limit feature maps CLDAT<1:0> bits to the PWMxH and PWMxL outputs. The PWM Fault feature maps FLTDAT<1:0> to the PWMxH and PWMxL outputs.

bit 14-10 **CLSRC<4:0>:** Current-Limit Control Signal Source Select for PWMx # Generator bits(2,3)
11111 = Reserved
•
•
•
01000 = Reserved

00111 = Fault 8
00110 = Fault 7
00101 = Fault 6
00100 = Fault 5
00011 = Fault 4
00010 = Fault 3
00001 = Fault 2
00000 = Fault 1

bit 9 **CLPOL:** Current-Limit Polarity for PWMx Generator # bit(1)
1 = The selected current-limit source is active-low
0 = The selected current-limit source is active-high

bit 8 **CLMOD:** Current-Limit Mode Enable bit for PWMx Generator # bit
1 = Current-limit function is enabled
0 = Current-limit function is disabled

Note 1: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

2: When Independent Fault mode is enabled (IFLTMOD<1:0> = 1), and Fault 1 is used for Current-Limit mode (CLSRC<4:0> = b0000), the Fault Control Source Select bits (FLTSRC<4:0>) should be set to an unused Fault source to prevent Fault 1 from disabling both the PWMxL and PWMxH outputs.

3: When Independent Fault mode is enabled (IFLTMOD<1:0> = 1) and Fault 1 is used for Fault mode (FLTSRC<4:0> = b0000), the Current-Limit Control Source Select bits (CLSRC<4:0>) should be set to an unused current-limit source to prevent the current-limit source from disabling both the PWMxH and PWMxL outputs.

16.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
   a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on SSx.
   b) If FRMPOL = 0, use a pull-up resistor on SSx.

Note:	This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using SSx from a master):
   a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on SSx.
   b) If CKP = 0, always place a pull-down resistor on SSx.

Note:	This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCK transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the SSx pin, which indicates the start of a data frame.

Note:	Not all third-party devices support Frame mode timing. Refer to the SPI electrical characteristics for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPI data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPI Shift register and is empty once the data transmission begins.

16.2 SPI Resources

Many useful resources related to SPI are provided on the Microchip web site (www.microchip.com).

16.2.1 KEY RESOURCES

- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33F/PIC24H Family Reference Manual"* Sections
- Development Tools

REGISTER 19-6: ADCPC1: ADC CONVERT PAIR CONTROL REGISTER 1 (CONTINUED)

bit 7 **IRQEN2:** Interrupt Request Enable 2 bit(2)
1 = Enables IRQ generation when requested conversion of channels AN5 and AN4 is completed
0 = IRQ is not generated

bit 6 **PEND2:** Pending Conversion Status 2 bit(2)
1 = Conversion of channels AN5 and AN4 is pending; set when selected trigger is asserted.
0 = Conversion is complete

bit 5 **SWTRG2:** Software Trigger 2 bit(2)
1 = Starts conversion of AN5 and AN4 (if selected by the TRGSRCx bits)(3)
This bit is automatically cleared by hardware when the PEND2 bit is set.
0 = Conversion has not started

bit 4-0 **TRGSRC2<4:0>:** Trigger 2 Source Selection bits(2)
Selects trigger source for conversion of analog channels AN5 and AN4.
11111 = Timer2 period match
•
•
•
11011 = Reserved
11010 = PWM Generator 4 current-limit ADC trigger
11001 = Reserved
11000 = PWM Generator 2 current-limit ADC trigger
10111 = PWM Generator 1 current-limit ADC trigger
10110 = Reserved
•
•
•
10010 = Reserved
10001 = PWM Generator 4 secondary trigger is selected
10000 = Reserved
01111 = PWM Generator 2 secondary trigger is selected
01110 = PWM Generator 1 secondary trigger is selected
01101 = Reserved
01100 = Timer1 period match
•
•
•
01000 = Reserved
00111 = PWM Generator 4 primary trigger is selected
00110 = Reserved
00101 = PWM Generator 2 primary trigger is selected
00100 = PWM Generator 1 primary trigger is selected
00011 = PWM Special Event Trigger is selected
00010 = Global software trigger is selected
00001 = Individual software trigger is selected
00000 = No conversion is enabled

Note 1: This bit is available in dsPIC33FJ06GS001/101A and dsPIC33FJ09GS302 devices only.
2: This bit is available in dsPIC33FJ06GS102A/201A and dsPIC33FJ09GS302 devices only.
3: The trigger source must be set as a global software trigger prior to setting this bit to '1'. If other conversions are in progress, conversion will be performed when the conversion resources are available.

22.4 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

22.4.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit (FWDT<4>). With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TWDT) of 1 ms in 5-bit mode or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC<2:0> bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

22.4.2 SLEEP AND IDLE MODES

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP bit (RCON<3>) or IDLE bit (RCON<2>) will need to be cleared in software after the device wakes up.

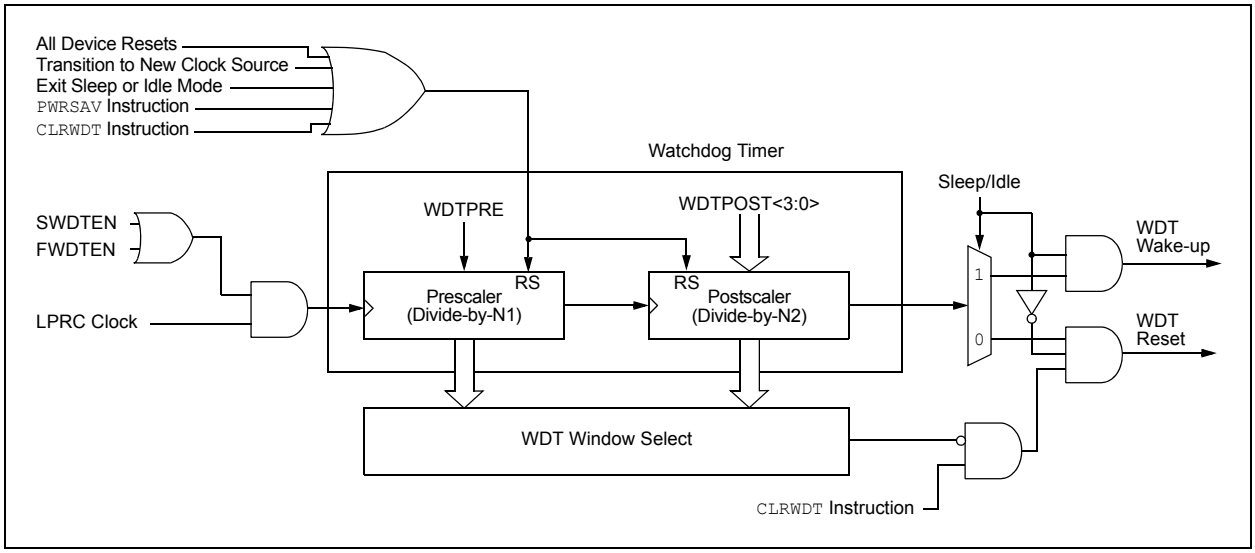
22.4.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register (FWDT<7>). When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

FIGURE 22-2: WDT BLOCK DIAGRAM



22.5 JTAG Interface

A JTAG interface is implemented, which supports boundary scan device testing, as well as in-circuit programming. Detailed information on this interface will be provided in future revisions of this document.

22.6 In-Circuit Serial Programming

The dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 family of digital signal controllers can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the digital signal controller just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33F/PIC24H Flash Programming Specification"* (DS70152) for details about In-Circuit Serial Programming (ICSP™).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

22.7 In-Circuit Debugger

The dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 devices provide simple debugging functionality through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{MCLR}$, VDD, VSS and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins.

TABLE 25-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current during Programming	—	10	—	mA	
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C(2)
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +125°C(2)
D138a	TWW	Word Write Cycle Time	42.3	—	55.9	µs	TWW = 355 FRC cycles, TA = +85°C(2)
D138b	TWW	Word Write Cycle Time	41.1	—	57.6	µs	TWW = 355 FRC cycles, TA = +125°C(2)

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `'b011111` (for Minimum), TUN<5:0> = `'b100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 25-20) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 "Programming Operations"**.

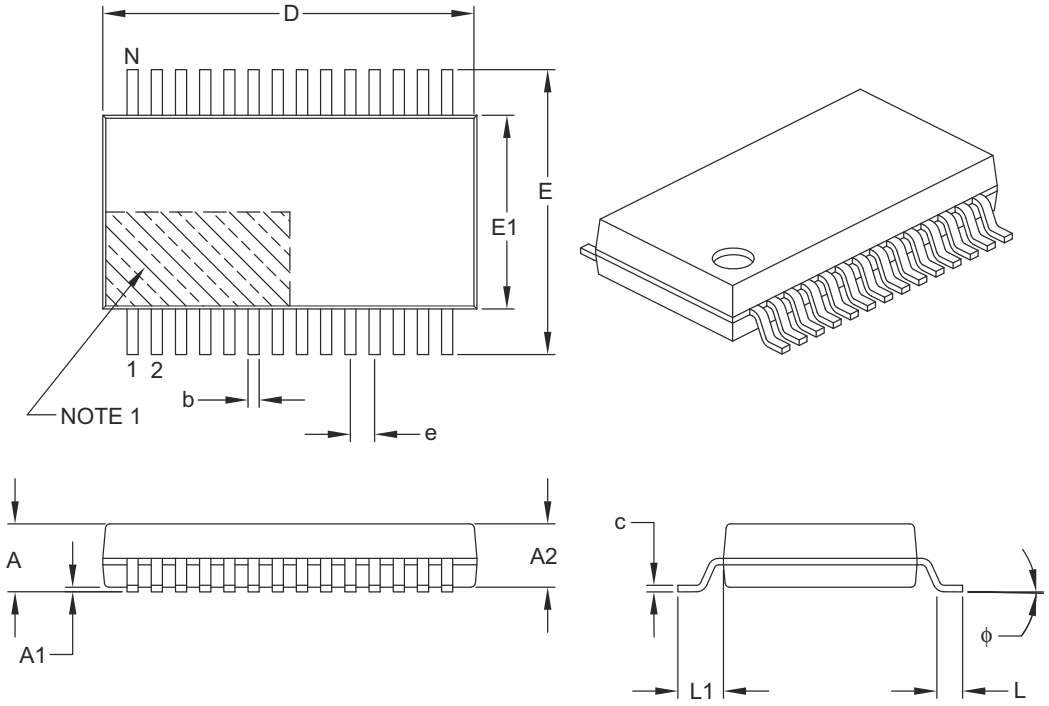
TABLE 25-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Operating Conditions:	-40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended						
Param.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
	CEFC	External Filter Capacitor Value(1)	4.7	10	—	µF	Capacitor must be low series resistance (< 0.5 Ohms)

Note 1: Typical VCAP voltage = 2.5 volts when VDD ≥ VDDMIN.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

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NOTES: